



MIDEM 2024

59th INTERNATIONAL CONFERENCE ON MICROELECTRONICS, DEVICES AND MATERIALS
WITH THE WORKSHOP ON ELECTROMAGNETIC COMPATIBILITY: FROM THEORY TO PRACTICE

October 2nd – 4th, 2024
Rimske Toplice, Slovenia

Announcement and Call for Papers

Chairs:

Assoc. Prof. Dr. Benjamin Lipovšek
Assoc. Prof. Dr. Marko Jankovec

IMPORTANT DATES

Abstract submission deadline:
May 17, 2024

Acceptance notification:
June 30, 2024

Full paper submission deadline:
August 31, 2024

Invited and accepted papers will be published in the Conference Proceedings.

Detailed and updated information about the MIDEM Conferences, as well as instructions for paper preparation, can be found on:

<http://www.midem-drustvo.si/>

GENERAL INFORMATION

The 59th International Conference on Microelectronics, Devices and Materials with the Workshop on Electromagnetic Compatibility: From Theory to Practice continues the successful tradition of annual international conferences organised by the MIDEM Society, the Society for Microelectronics, Electronic Components and Materials. The conference will be held in Rimske Toplice, Slovenia, from **OCTOBER 2nd – 4th, 2024**.

Topics of interest include but are not limited to:

- Electromagnetic compatibility (workshop topic)
- Novel monolithic and hybrid circuit processing techniques,
- New device and circuit design,
- Process and device modelling,
- Semiconductor physics,
- Sensors and actuators,
- Electromechanical devices, microsystems and nanosystems,
- Nanoelectronics,
- Optoelectronics,
- Photovoltaics,
- Electronic materials science and technology,
- New electronic materials and applications,
- Materials characterization techniques,
- Reliability and failure analysis,
- Education in microelectronics, devices and materials.

ORGANIZER:

MIDEM Society - Society for Microelectronics, Electronic Components and Materials, Slovenia

PARTNERS:

UL FE, IJS, IMAPS - Slovenia Chapter, IEEE - Slovenia Section

